

Title (en)

IRON-BASED ALLOY FOR POWDER INJECTION MOLDING

Title (de)

LEGIERUNG AUF EISENBASIS FÜR PULVER-SPRITZGUSS

Title (fr)

ALLIAGE À BASE DE FER POUR UN MOULAGE PAR INJECTION DE POUDRE

Publication

**EP 2770074 A4 20160420 (EN)**

Application

**EP 12841059 A 20120420**

Priority

- KR 20110108028 A 20111021
- KR 2012003071 W 20120420

Abstract (en)

[origin: EP2770074A1] A ferrous alloy for powder injection molding is provided. The ferrous alloy for powder injection molding includes iron (Fe) at 52.59-78.15 wt%, chromium (Cr) at 16.45-37.34 wt%, boron (B) at 3.42-7.76 wt%, silicon (Si) at 1.64-1.92wt%, sulfur (S) at 0-0.21 wt%, carbon (C) at 0.16-0.18 wt%, and other inevitable impurities.

IPC 8 full level

**C22C 38/00** (2006.01); **B22F 3/12** (2006.01); **B22F 3/22** (2006.01); **C22C 30/00** (2006.01); **C22C 33/02** (2006.01); **C22C 38/32** (2006.01); **C22C 38/34** (2006.01); **C22C 38/42** (2006.01); **C22C 38/48** (2006.01); **C22C 38/60** (2006.01)

CPC (source: EP KR US)

**B22F 3/12** (2013.01 - US); **B22F 3/225** (2013.01 - EP KR US); **C22C 30/00** (2013.01 - EP KR US); **C22C 33/0285** (2013.01 - EP KR US); **C22C 38/32** (2013.01 - EP KR US); **C22C 38/34** (2013.01 - EP KR US); **C22C 38/42** (2013.01 - EP US); **C22C 38/48** (2013.01 - EP US); **C22C 38/60** (2013.01 - EP US)

Citation (search report)

- [A] WO 2008002001 A1 20080103 - UNIV POHANG [KR], et al
- [A] DE 4441016 A1 19950629 - SAMSUNG HEAVY IND [KR]
- [A] EP 0745698 A1 19961204 - SAMSUNG HEAVY IND [KR]
- See references of WO 2013058453A1

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CZ305979B6

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 2770074 A1 20140827**; **EP 2770074 A4 20160420**; CN 103890210 A 20140625; CN 103890210 B 20160504; JP 2014534344 A 20141218; JP 5819001 B2 20151118; KR 101350944 B1 20140116; KR 20130043871 A 20130502; US 2014227124 A1 20140814; WO 2013058453 A1 20130425

DOCDB simple family (application)

**EP 12841059 A 20120420**; CN 201280051137 A 20120420; JP 2014536968 A 20120420; KR 20110108028 A 20111021; KR 2012003071 W 20120420; US 201214349122 A 20120420